Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Typ.	(N2X) 028 SSOP .209in Matte Tin	Termination Base Alloy: Copper Alloy (Cu) 28 SSOP .209in Matte Tin			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				JEDEC 97 Product Marking and/or Pkg. Labeling e3	
	1	"Contained In"	% Total	1	1		1			
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	182.90	(mg) Total	Mold Compound	% ot Total Weight	79.8
Silica, vitreous	60676-86-0	Mold Compound	67.830	155.466	678,300		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin (No bromine, No diantimony trioxide)	Trade Secret	Mold Compound	4.888	11.203	48,878		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin (No Br / CL SbO3, No diantimony trioxide)	Trade Secret	Mold Compound	4.888	11.203	48,878		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.955	4.481	19,551		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.239	0.549	2,394		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	10.031	22.992	100,314			Total	100.00	
Iron	7439-89-6	Lead Frame	0.247	0.566	2,468	24.07	(mg) Total	Lead Frame	% of Total Weight	10.5
Silver	7440-22-4	Lead Frame	0.200	0.458	2,000		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.013	0.030	131		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.009	0.020	87		Silver	7440-22-4	1.91	
Silver (Ag)	7440-22-4	Die Attach	0.563	1.289	5,625		Zinc	7440-66-6	0.13	
Modified Epoxy Resin	13561-08-5	Die Attach	0.105	0.241	1,050		Phosphorous	7723-14-0	0.08	
Diglycidylether of bisphenol-F	54208-63-8	Die Attach	0.056	0.129	563			Total	100.00	
Modified Amine	827-43-0	Die Attach	0.026	0.060	263	1.72	(mg) Total	Die Attach	% of Total Weight	0.75
Silicon	7440-21-3	Chip (Die)	7.500	17.190	75,000		Silver (Ag)	7440-22-4	75.00	
Gold	7440-57-5	Wire Bond	0.200	0.458	2,000		Modified Epoxy Resin	13561-08-5	14.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	2.865	12,500	Dig	glycidylether of bisphenol-F	54208-63-8	7.50	
		TOTALS:	100.000	229.200	1,000,000		Modified Amine	827-43-0 Total	3.50 100.00	
	0.2292	q Total Mass							100.00	
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